

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Rajendra D. Pendse	01/03/2005
RECEIVING PARTY DATA	
Name:	ChipPAC, Inc.
Street Address:	47400 Kato Road
City:	Fremont
State/Country:	CALIFORNIA
Postal Code:	94538
PROPERTY NUMBERS Total: 3	
Property Type	Number
Application Number:	60518864
Application Number:	60533918
Application Number:	10985654
CORRESPONDENCE DATA	
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Total Attachments: 2	
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PATENT
REEL: 015539 FRAME: 0144

**SOLE TO CORPORATE
ASSIGNMENT**

WHEREAS, the undersigned Rajendra D. Pendse, hereinafter termed the "Inventor" has invented certain new and useful improvements in:

Bump-on-Lead Flip Chip Interconnection

and has filed provisional applications for United States patent disclosing and identifying the invention, the first said provisional application having been filed on November 10, 2003 as U.S. Application No. 60/518,864; and said second provisional application having been filed on December 31, 2003 as U.S. Application No. 60/533,918; and has filed a non-provisional application for United States patent disclosing and identifying the above invention, the non-provisional application having been filed on November 10, 2004 as U.S. Application No. 10/985,654; and has executed an oath or declaration of inventorship for such non-provisional application on:

the 3rd day of January, 2005,

hereinafter termed the "Applications"; and

WHEREAS, ChipPAC, Inc., a corporation of the state of Delaware, having a place of business at 47400 Kato Road, Fremont, California 94538 (hereinafter termed the "Assignee") is desirous of acquiring the entire right, title and interest in and to the Applications and the invention disclosed therein, and in and to any and all embodiments of the invention, heretofore conceived, made, or discovered jointly or severally by said Inventor (all collectively hereinafter termed the "Invention") and in and to any and all patents, inventors' certificates, and other forms of protection (hereinafter termed the "Patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged by the Inventor:

1. The Inventor has assigned to the Assignee, and does hereby sell, assign, transfer and convey to the Assignee all right, title and interest (a) in and to the Invention and the Application; and (b) in and to all rights to apply for foreign patents (including patent, utility model and industrial designs) on the Invention pursuant to the International Convention for the Protection of Industrial Property or otherwise, including the right to claim priority from the Application; and (c) in and to any and all applications filed and any and all patents granted on the Invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extension of any of said patents.

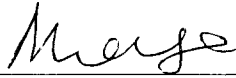
2. The Inventor hereby covenants and agrees to cooperate with the Assignee to enable the Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by the Inventor shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by the Assignee (a) for perfecting in the Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering the Invention; (d) for filing and prosecuting applications for reissuance of any said Patents; (e) for interference or other priority proceedings involving the Invention; and (f) for legal proceedings involving the Invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use

proceedings, infringement actions and court actions; provided, however, that the expense incurred by the Inventor in providing such cooperation shall be paid for by the Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representatives, and shall be binding upon the Inventor, his heirs, legal representatives and assigns.

4. The Inventor hereby warrants and represents that he has not entered into and will not enter into any assignment, contract, or understanding in conflict herewith.

IN TESTIMONY WHEREOF, the Inventor has executed and delivered this instrument to the Assignee as of the date written below.



Rajendra D. Pendse

3 Jan. 2005

Date